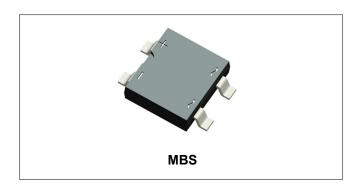






MB05S THRU MB10S

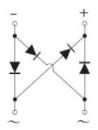
Single-Phase 0.8A Surface Mount Glass Passivated Bridge Rectifier



Features

- Glass passivated die construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-30A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0
- This is a Pb Free Device
- . All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Mechanical Data

- Case: Reliable low cost construction utilizing molded plastic technique
- Terminals: Plated Leads Solderable per MIL STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any

Maximum Ratings @T_A=25°C unless otherwise specified

Type Number	Symbol	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Peak Repetitive Reverse Voltage DC Blocking Voltage	V _{RRM} V _{DC}	50	100	200	400	600	800	1000	V
RMS Voltage	V _{RMS}	35	70	140	280	420	480	700	V
Average Rectified Output Current (Note1)@T _A =40°C (Note 2)@T _A =40°C	lo				0.5 0.8				Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30				Α			

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Electrical Characteristics:@TA=25°C unless otherwise specified

Type Number	Symbol	MB05S MB1S	MB2S MB49	MB6S	MB8S	MB10S	Units
Forward Voltage per element @I _F =0.8A	V_{FM}		1.1				V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 125°C	I _R		5 500				μA
Typical Junction Capacitance (Note 3)	Cj		13				pF

^{*} Pulse width < 300 μ s, duty cycle < 2%

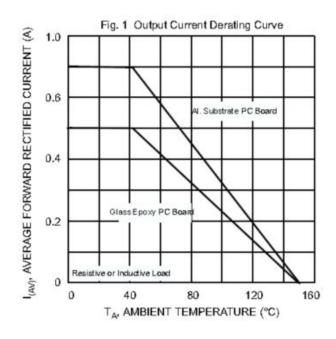
Thermal-Mechanical Specifications:@TA=25°C unless otherwise specified

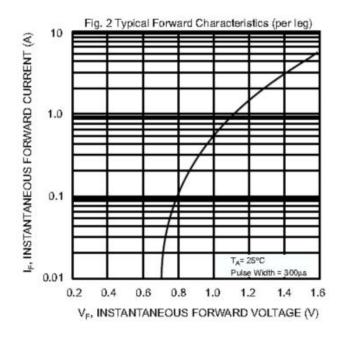
Type Number	Symbol	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Tunical Thornal Desistance novice	R _{θJA} 70			°C/W					
Typical Thermal Resistance per leg	ReJL	20							0/00
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	тд -55+150			°C				

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

- 2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.
- 3. Measured at 1.0 MHZ and applied reverse voltage of 4.0 VDC

Ratings and Characteristics Curves



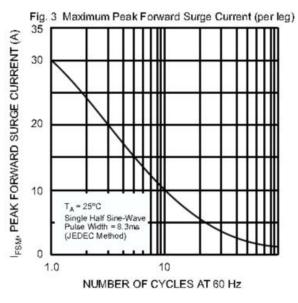


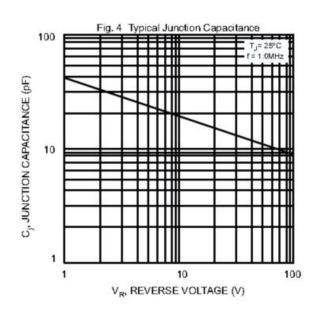
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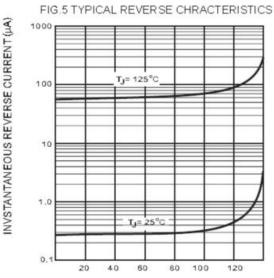












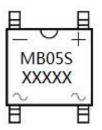
PERCENT OF RATED PEAK INVERSE VOLTGE (V)

Ordering Information

Device	Package	Shipping		
MB05S THRU MB10S	MBS (Pb-Free)	3000pcs / reel		

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

MB05S = Type Number
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin

Epoxy resin UL:94V-0

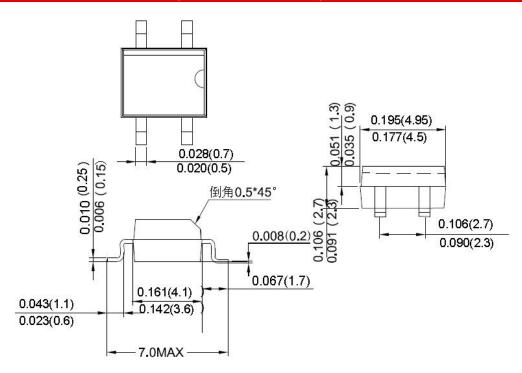
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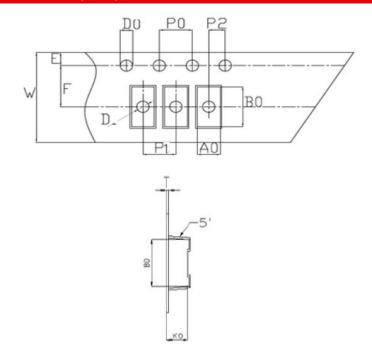




Mechanical Dimensions MBS(Inches/Millimeters)



Carrier Tape Specification MBS



SYMBOL	Millimeters					
STWIDOL	Min.	Max.				
A0	4.92	5.12				
В0	7.12	7.32				
D0	1.50	1.60				
D1	1.40	1.60				
P0	3.90	4.10				
P1	7.90	8.10				
P2	1.95	2.05				
E	1.65	1.85				
K0	2.78	2.98				
F	5.45	5.55				
W	11.90	12.10				
Т	0.24	0.30				
10P0	39.80	40.20				
抗拉拉力	≥3KG					

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